

Title (en)

FLEXIBLE LAMINATE FOR PRINTED CIRCUIT BOARD AND PROCESS FOR ITS PRODUCTION.

Title (de)

FLEXIBLES LAMINAT FUR PLATINE FUR GEDRUCKTE SCHALTKREISE UND VERFAHREN ZU SEINER HERSTELLUNG.

Title (fr)

LAMINATE FLEXIBLE POUR DES CARTES DE CIRCUIT IMPRIME ET PROCEDE DE PRODUCTION.

Publication

EP 0243507 A4 19890427 (EN)

Application

EP 86906455 A 19861031

Priority

- JP 24293585 A 19851031
- JP 25590886 A 19861029

Abstract (en)

[origin: WO8702620A1] A polyimide film obtained by using as starting materials a symmetric aromatic m-substituted primary diamine and a symmetric aromatic P-substituted primary diamine in a given proportion. This film has excellent heat resistance, electric properties, and flexibility. In providing this film on a substrate, a precursor of the polyimide, i.e. a polyamic acid, is applied to the substrate without using any adhesives, and a reaction is allowed to proceed to form a polyimide to thereby provide the polyimide film on the substrate with good adhesiveness. The resulting flexible printed circuit board has the above-described excellent properties.

IPC 1-7

B32B 15/08; **H05K 3/38**; **H05K 1/03**; **C08G 73/10**

IPC 8 full level

B32B 15/00 (2006.01); **B32B 15/08** (2006.01); **C08G 69/26** (2006.01); **C08G 73/10** (2006.01); **H01B 3/30** (2006.01); **H05K 1/03** (2006.01); **H05K 3/38** (2006.01)

CPC (source: EP US)

C08G 69/265 (2013.01 - EP US); **C08G 73/1042** (2013.01 - EP US); **C08G 73/105** (2013.01 - EP US); **C08G 73/1064** (2013.01 - EP US); **C08G 73/1071** (2013.01 - EP US); **H01B 3/306** (2013.01 - EP US); **H05K 1/0346** (2013.01 - EP US); **Y10S 428/901** (2013.01 - EP US); **Y10T 428/24917** (2015.01 - EP US); **Y10T 428/31681** (2015.04 - EP US); **Y10T 428/31721** (2015.04 - EP US)

Citation (search report)

- [XP] EP 0167020 A2 19860108 - AKZO GMBH [DE]
- [A] US 3793281 A 19740219 - ACLE L
- See references of WO 8702620A1

Cited by

EP0367482A1; EP0605112A3; EP0383461A3; EP0500292A1; US5346982A; US5288843A; US5380805A; US5380820A; US5459233A; US5506311A

Designated contracting state (EPC)

CH DE FR GB IT LI NL

DOCDB simple family (publication)

WO 8702620 A1 19870507; DE 3684307 D1 19920416; EP 0243507 A1 19871104; EP 0243507 A4 19890427; EP 0243507 B1 19920311; US 4839232 A 19890613

DOCDB simple family (application)

JP 8600554 W 19861031; DE 3684307 T 19861031; EP 86906455 A 19861031; US 6944987 A 19870625